





2025-2026 Undergraduate Research Experience and Mentoring (REM) Program

What is involved? (12 month commitment)

- 8 weeks summer research (June July 2025)
- Research project poster to present at Emerging Researcher National (ERN) conference (Spring 2026)
- Regular meetings with project mentors (Aug '25-May '26)
- Mentoring sessions with education coordinators

What you will receive:

- \$6,500 stipend for summer research
- Necessary summer travel and lodging fully covered
- \$1,000 stipend in Fall 2025
- \$1,000 stipend in Spring 2026
- All expenses paid trip to ERN conference
- STEM mentors
- Graduate school/internship prep sessions

Who is eligible?

Students from the University of Arizona, Wayne State, and Spelman College who have also completed their sophomore year by beginning of this REM program are eligible.

RESEARCH PROJECTS

For more information on projects visit newfos.arizona.edu/education/rem

Building Emerging Technologies with Surface Acoustic Waves - Location: University of Arizona Design, build, and optimize cutting-edge Surface Acoustic Wave (SAW) devices, gain hands-on experience in a state-of-the-art cleanroom, and develop skills for exciting careers in semiconductors, RF technologies, and beyond.

Fabrication of reconfigurable acoustic devices - Location: University of Arizona

Synthesize phase-change materials from scratch, fabricate acoustic circuits using laser writing, and create waveguides that guide sound waves by switching between crystal and glass phases.

Miniaturized Acoustic Waveguides for Quantum-Inspired Computing: A Finite Element Analysis

Approach - Location: Wayne State University

Learn finite element analysis (FEA) to model miniaturized acoustic waveguides for quantum-inspired computing and design and simulate waveguides in COMSOL.

Experimental Demonstration of Topological Modes in a Su–Schrieffer–Heeger (SSH) System -

Location: Spelman College; Georgia Tech

Modifying an air track to conduct experiments on protected edge modes AND gain skills in mechanical design, CAD, and 3D printing.

Applications due: March 17, 2025

